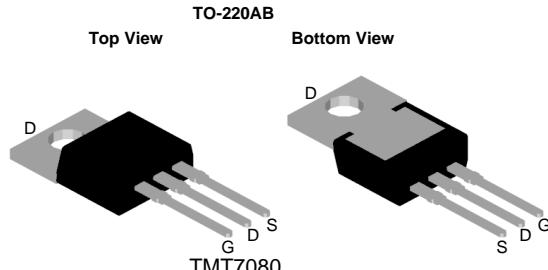
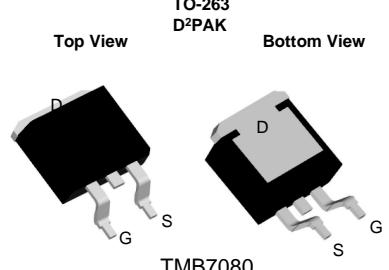


## TMT7080 / TMB7080 N-CHANNEL ENHANCEMENT MOSFET

<b>General Description</b> <p>The TMT7080 &amp; TMB7080 uses Trench MOSFET technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of <math>R_{DS(ON)}</math>, Ciss and Coss. This device is ideal for boost converters and synchronous rectifiers for consumer, telecom, industrial power supplies and LED backlighting.</p>	<b>Product Summary</b> <table style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 30%;">V<sub>DS</sub></td><td style="width: 30%;">70V</td></tr> <tr> <td>I<sub>D</sub> (at V<sub>GS</sub>=10V)</td><td>80A</td></tr> <tr> <td>R<sub>DS(ON)</sub> (at V<sub>GS</sub>=10V)</td><td>&lt; 7.2mΩ</td></tr> </table> <p>100% UIS Tested 100% R<sub>g</sub> Tested</p>	V <sub>DS</sub>	70V	I <sub>D</sub> (at V <sub>GS</sub> =10V)	80A	R <sub>DS(ON)</sub> (at V <sub>GS</sub> =10V)	< 7.2mΩ
V <sub>DS</sub>	70V						
I <sub>D</sub> (at V <sub>GS</sub> =10V)	80A						
R <sub>DS(ON)</sub> (at V <sub>GS</sub> =10V)	< 7.2mΩ						
 TO-220AB Top View      Bottom View  TO-263 D <sup>2</sup> PAK Top View      Bottom View <b>TMB7080</b>	 RoHS Compliant						

**ABSOLUTE MAXIMUM RATINGS** T<sub>A</sub> = 25 °C, unless otherwise noted

Symbol	Parameter	Typical	Unit
V <sub>DSS</sub>	Drain-Source Voltage	70	V
V <sub>GSS</sub>	Gate-Source Voltage	$\pm 25$	V
I <sub>D</sub>	Continuous Drain Current(T <sub>J</sub> =150°C)	80	A
I <sub>DM</sub>	Pulsed Drain Current	320	A
T <sub>J</sub>	Operation Junction Temperature	-55~150	°C
T <sub>STG</sub>	Storage Temperature Range	-55~150	°C
P <sub>D</sub>	Power Dissipation(T <sub>C</sub> =25 °C)	100	W
E <sub>AS</sub>	Single Pulse Avalanche Energy (T <sub>J</sub> =25 °C, V <sub>DD</sub> =40V, V <sub>GS</sub> =10V, R <sub>G</sub> =25Ω)	410	mJ
R <sub>θJC</sub>	Thermal Resistance-Junction to Ambient	1.25	°C/W

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

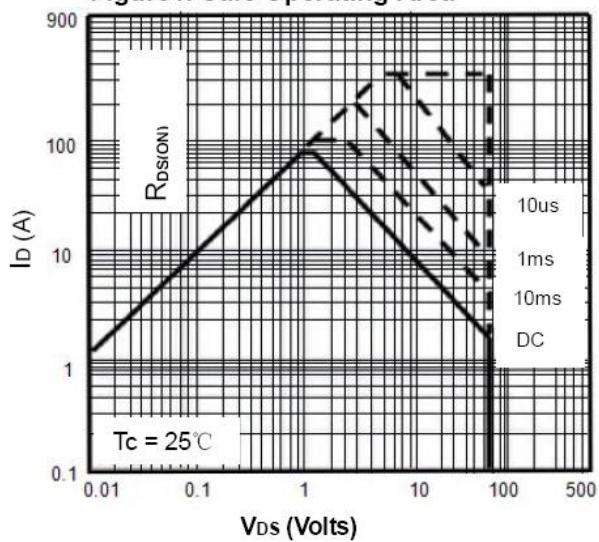
**Electrical Characteristics ( $T_A=25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	Condition	Min	Typ	Max	Unit	
<b>Static Parameters</b>							
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_{DS}=250\mu\text{A}$	70	-	-	V	
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{CS}, I_{DS}=250\mu\text{A}$	2	-	4	V	
$I_{GSS}$	Gate Leakage Current	$V_{DS}=0\text{V}, V_{GS}=\pm 20\text{V}$	-	-	$\pm 100$	nA	
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=68\text{V}, V_{GS}=0\text{V}$ $T_C=25^\circ\text{C}$	-	-	1	$\mu\text{A}$	
		$V_{DS}=68\text{V}, V_{GS}=0\text{V}$ $T_C=125^\circ\text{C}$	-	-	10	$\mu\text{A}$	
$R_{DS(\text{ON})}$	Drain-Source On-Resistance	$V_{GS}=10\text{V}, I_{DS}=40\text{A}$	-	5.9	7.2	$\text{m}\Omega$	
<b>Source-Drain Diode</b>							
$I_S$	Diode Forward Current (Max.)		-	92	-	A	
$V_{SD}$	Diode Forward Voltage	$I_S=40\text{A}, V_{GS}=0\text{V}$		0.69	0.95	V	
<b>Dynamic Parameters</b>							
$Q_g$	Total Gate Charge	$V_{DS}=50\text{V}, V_{GS}=10\text{V}$ $I_D=40\text{A}$	-	82	-	nC	
$Q_{gs}$	Gate-Source Charge		-	16.2	-		
$Q_{gd}$	Gate-Drain Charge		-	36.7	-		
$C_{iss}$	Input Capacitance	$V_{DS}=25\text{V}, V_{GS}=0\text{V}$ $F=1\text{MHz}$	-	3483	-	pF	
$C_{oss}$	Output Capacitance		-	459	-		
$C_{rss}$	Reverse Transfer Capacitance		-	214	-		
$t_{d(on)}$	Turn-On Time	$V_{DS}=30\text{V}, R_L=15\Omega$ $V_{GS}=10\text{V}, R_G=2.5\Omega$ $I_D=2\text{A}$	-	11	-	nS	
$t_r$			-	13	-		
$t_{d(off)}$	Turn-Off Time		-	22	-		
$t_f$			-	37	-		

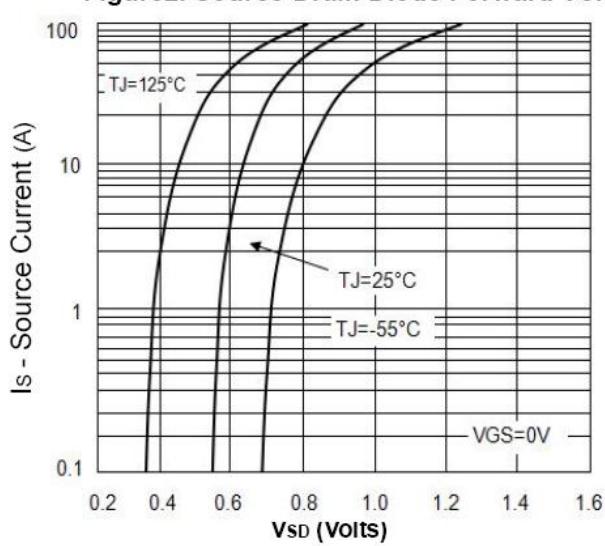
Note: 1. Pulse test: pulse width  $\leqslant 300\text{us}$ , duty cycle  $\leqslant 2\%$ ;

2. Static parameters are based on package level with recommended wire-bonding

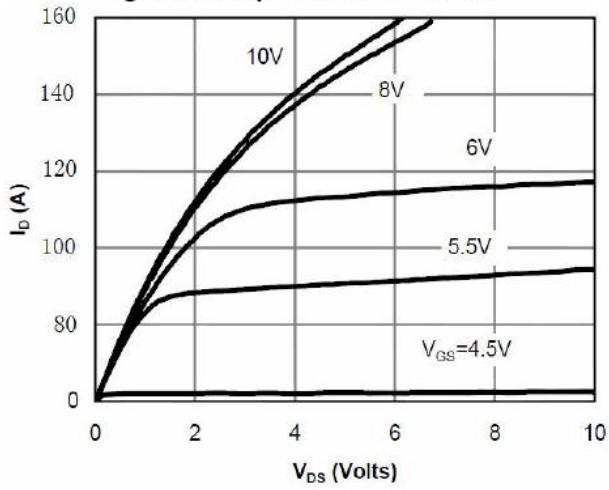
**Figure1. Safe Operating Area**



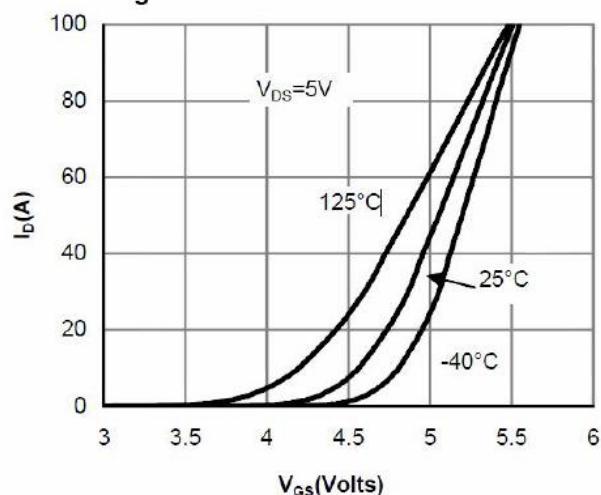
**Figure2. Source-Drain Diode Forward Voltage**



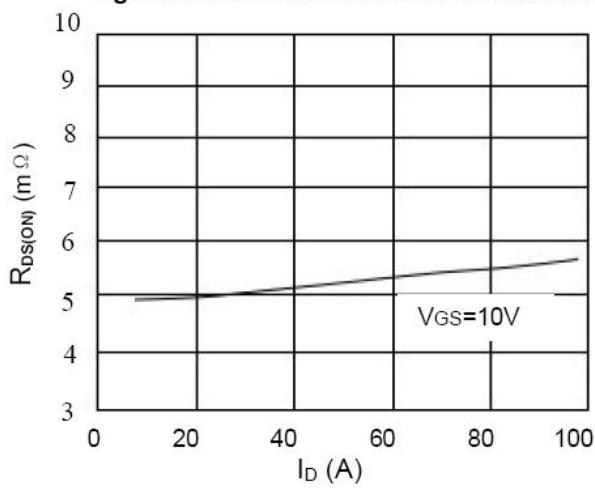
**Figure3. Output Characteristics**



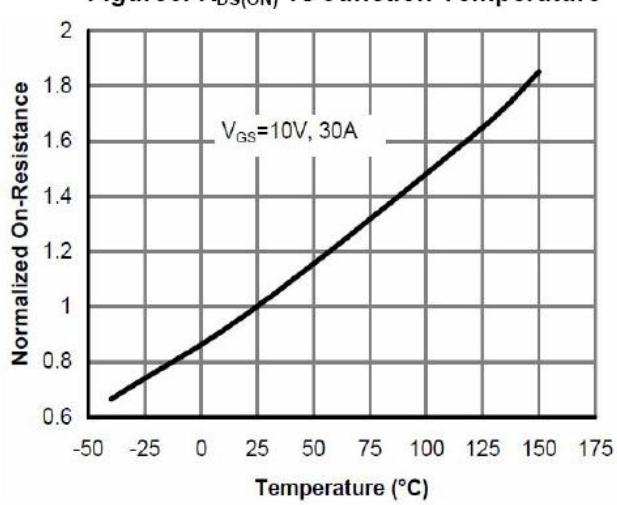
**Figure4. Transfer Characteristics**



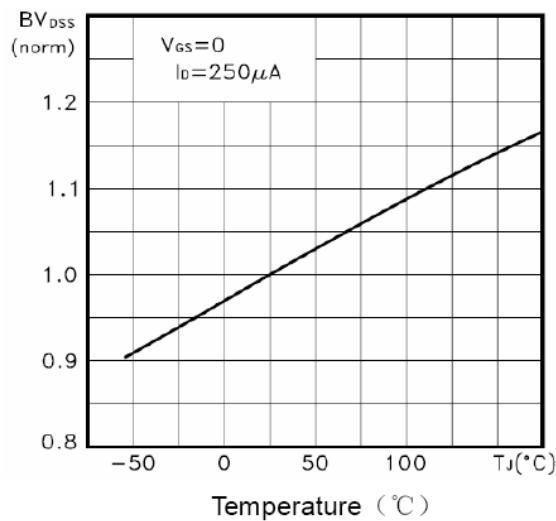
**Figure5. Static Drain-Source On Resistance**



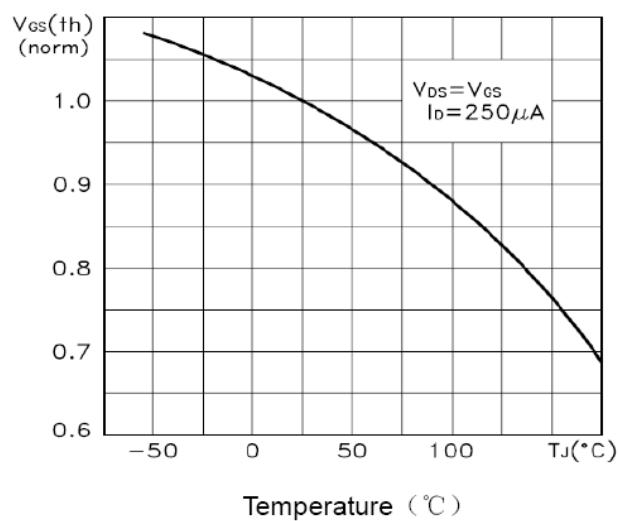
**Figure6.  $R_{DS(\text{ON})}$  vs Junction Temperature**



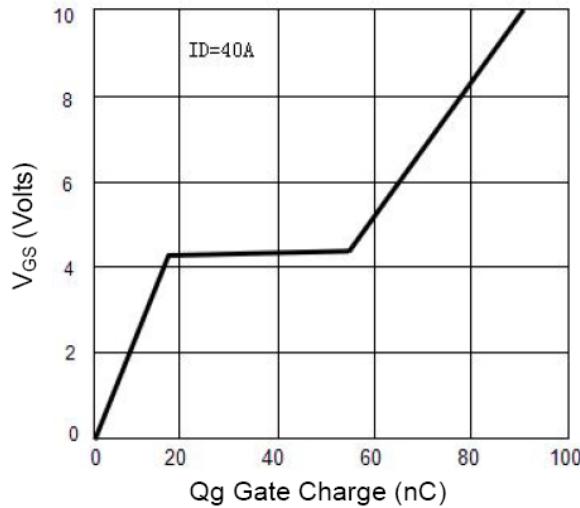
**Figure7.  $BV_{DSS}$  vs Junction Temperature**



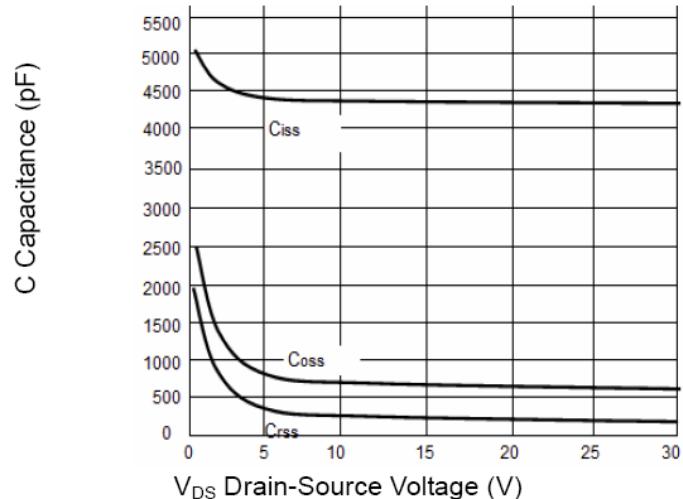
**Figure8.  $V_{GS(th)}$  vs Junction Temperature**



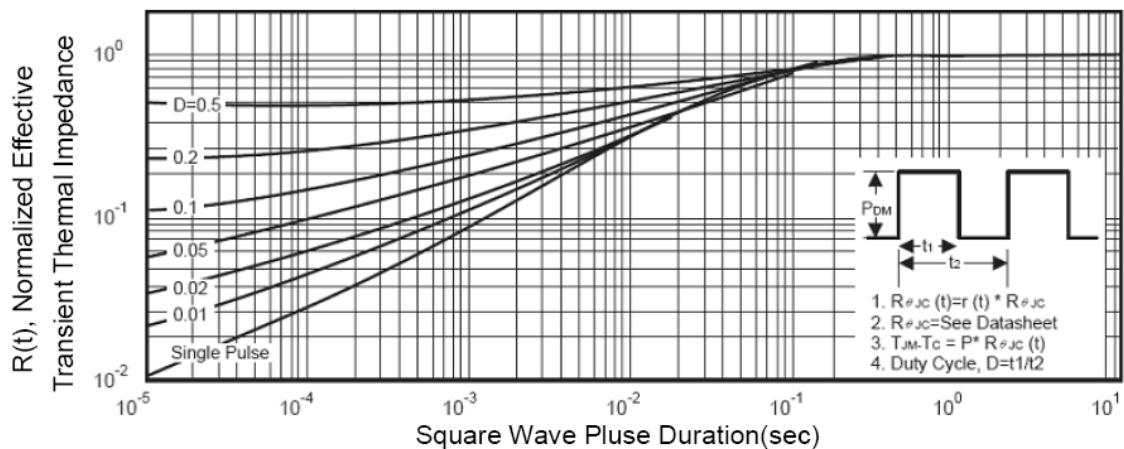
**Figure9. Gate Charge Waveforms**



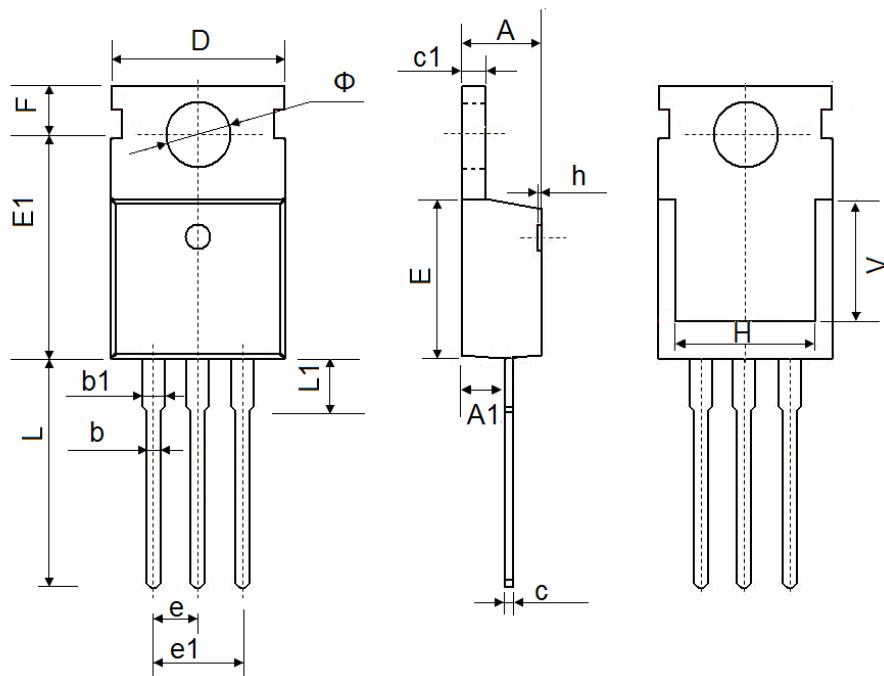
**Figure10. Capacitance**



**Figure11. Normalized Maximum Transient Thermal Impedance**

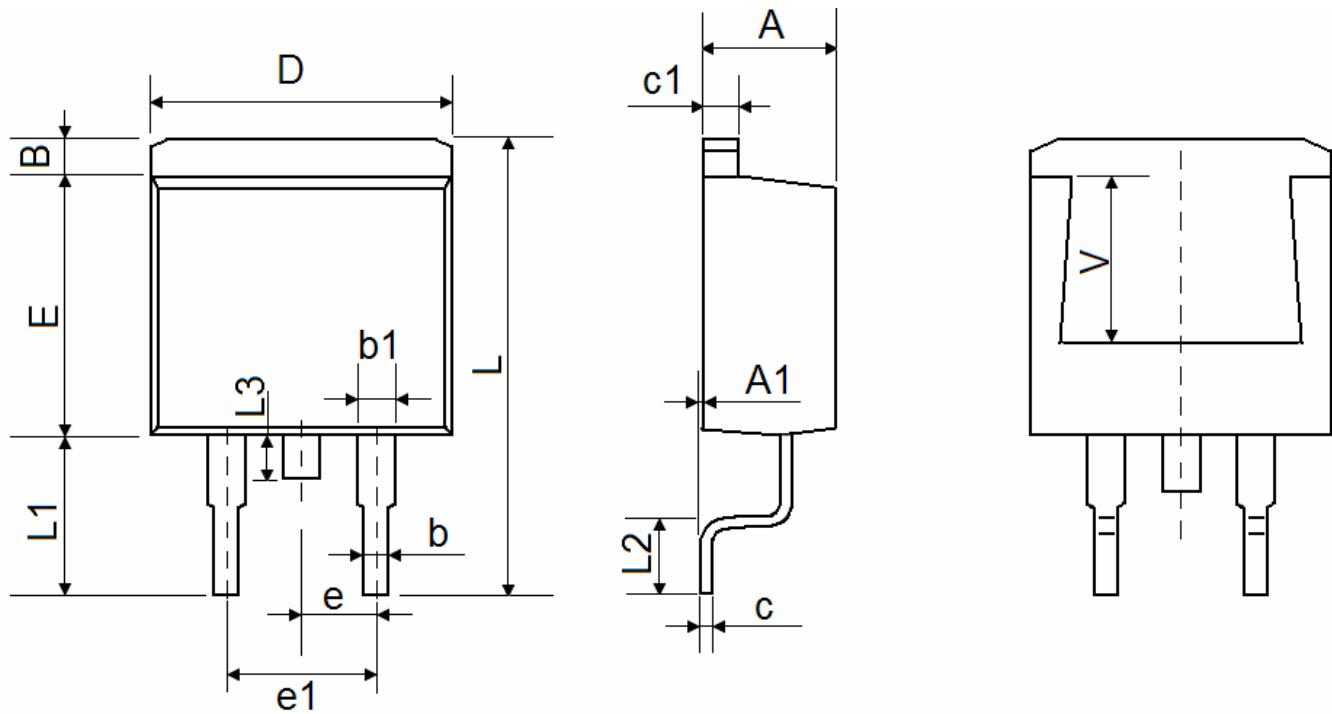


## TO-220AB Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.400	4.600	0.173	0.181
A1	2.250	2.550	0.089	0.100
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
c	0.330	0.650	0.013	0.026
c1	1.200	1.400	0.047	0.055
D	9.910	10.250	0.390	0.404
E	8.9500	9.750	0.352	0.384
E1	12.650	12.950	0.498	0.510
e	2.540 TYP.		0.100 TYP.	
e1	4.980	5.180	0.196	0.204
F	2.650	2.950	0.104	0.116
H	7.900	8.100	0.311	0.319
h	0.000	0.300	0.000	0.012
L	12.900	13.400	0.508	0.528
L1	2.850	3.250	0.112	0.128
V	7.500 REF.		0.295 REF.	
Φ	3.400	3.800	0.134	0.150

## TO-263 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.470	4.670	0.176	0.184
A1	0.000	0.150	0.000	0.006
B	1.170	1.370	0.046	0.054
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
c	0.310	0.530	0.012	0.021
c1	1.170	1.370	0.046	0.054
D	10.010	10.310	0.394	0.406
E	8.500	8.900	0.335	0.350
e	2.540 TYP.		0.100 TYP.	
e1	4.980	5.180	0.196	0.204
L	15.050	15.450	0.593	0.608
L1	5.080	5.480	0.200	0.216
L2	2.340	2.740	0.092	0.108
L3	1.300	1.700	0.051	0.067
V	5.600 REF		0.220 REF	